## **MA22D15**

## Silicon epitaxial planar type

#### For high frequency rectification

#### ■ Features

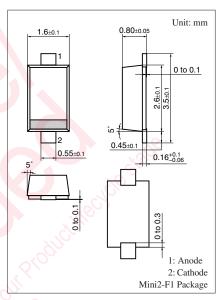
- $I_{F(AV)} = 1$  A rectification is possible
- Low forward voltage V<sub>F</sub>
- Low reverse current I<sub>R</sub>

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	$V_R$	20	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	25	V	
Forward current (Average) *1	I <sub>F(AV)</sub>	1.0	A	
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	20	A	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55  to + 150	°C	

Note) \*1: Mounted on a alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

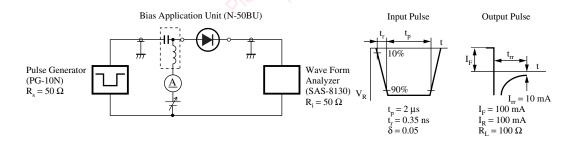


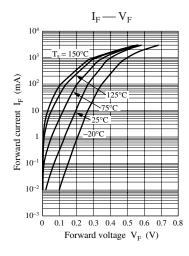
Marking Symbol: 3R

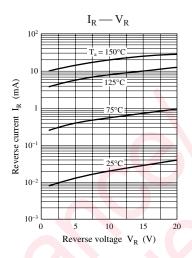
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

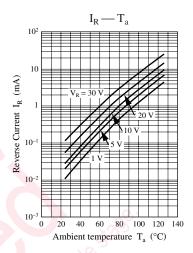
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 1.0 \text{ mA}$	100	0.40	0.43	V
Reverse current	$I_R$	$V_R = 20 \text{ V}$		<b>)</b>	100	μΑ
Terminal capacitance	$C_t$	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$	500	30		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		10		ns
~C <sub>C</sub> ,		$I_{rr} = 10 \text{ mA}$ , $R_L = 100 \Omega$				

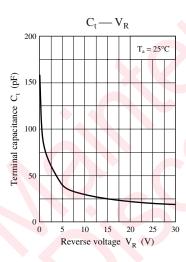
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measuring instrument











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